**THAPAR INSTITUTE OF ENGINEERING & TECHNOLOGY, PATIALA**

(Deemed to be University)

CENTRE FOR INDUSTRIAL LIAISON AND PLACEMENT

Dated: 24.07.2024

CAMPUS INTERVIEWS

1. Name of the Organization: **Alvarez and Marsal Global**

**(**[**www.alvarezandmarsal.com**](http://www.alvarezandmarsal.com)**)**

Branches of Engineering: BE MBA-EC only

Eligibility Criteria 10th, 10+2/Dip. 65%

Graduation – All years separately 6.50

Present CGPA 6.50

No backlog courses at present.

Process of Interviews: Shortlisting based upon details

Virtual two rounds of interviews

2. **Virtual PPT will be on be on 30th, July, 2024 at 4.00 PM**

**Virtual Interviews will be on 5th, August, 2024.**

3 Submit the details & resume to the below TIET Google link by 29th July, 2024 by 9.00 A.M

[**https://forms.gle/D4YXK6WFAsBjFPZ37**](https://forms.gle/D4YXK6WFAsBjFPZ37)

4. CTC ~ Stipend – Rs. 30,000/- P.M. during internship

|  |  |
| --- | --- |
| Compensation break-up | (INR) |
| Total Fixed | 12,00,000 |
| Performance Bonus (maximum earning potential - 30%) | 3,39,623 |
| Joining Bonus (2-year claw back period) | 2,00,000 |
| Gratuity | 27,213 |
| Medical Insurance (Group + Term Life + Accidental) | 45,000 |
| **Total** | **18,11,836** |

Job Location: Gurgaon, Haryana

Internship + FTE

(H.S.Bawa)

Head CILP

CC: HECED - for kind information please

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CENTRE FOR INDUSTRIAL LIAISON AND PLACEMENT

Dated: 24.07.2024

CAMPUS INTERVIEWS

1. Name of the Organization: **Cloudera**

**(**[**www.cloudera.com**](http://www.cloudera.com)**)**

**Profile enclosed**

Branches of Engineering: BE – CS

M.E -CS

Eligibility Criteria 10th, 10+2/Dip. 80%

Graduation for PG 80%

Present CGPA 8.00 & above

No backlogs and no educational gap

Process of Interviews: Short listing based upon your details.

Virtual Online tests

Virtual Interviews

2. **PPT and Online test will be on \_\_\_August, 2024**

**Interviews will be on \_\_\_\_August,2024**

3 Submit the details & resume to the below TIET Google link by 29th July, 2024 by 9.00 A.M

[**https://forms.gle/6Jfqrh4KsEjZAW8GA**](https://forms.gle/6Jfqrh4KsEjZAW8GA)

4. CTC ~ Stipend during internship - Rs. 45,000/- PM

CTC ~  Rs. 20.11 LPA (Rs. 18,00,000 base salary) + Benefits

PPO subjected to performance during internship

Job location- Bangalore

Internship + PPO - subjected to performance during internship

(H.S.Bawa)

Head CILP

CC: HCSED - for kind information please

**THAPAR INSTITUTE OF ENGINEERING & TECHNOLOGY, PATIALA**

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CENTRE FOR INDUSTRIAL LIAISON AND PLACEMENT

Dated: 24.07.2024

CAMPUS INTERVIEWS

1. Name of the Organization: **ION Group**

**(**[**www.iongroup.com**](http://www.iongroup.com)**)**

**(Profile enclosed )**

**Software Developer**

**Technical Analyst**

**Data Scientist**

Branches of Engineering: BE- CS/EE/EIC/EC/ENC/EEC

Eligibility Criteria 10th, 10+2/Dip. 75 %

Present CGPA 7.50

No backlog courses at present.

Process of Interviews: Shortlisting based upon details

Online Test

Five rounds of Interviews (Technical, Case Study, Stakeholder, Culture Fit and Future Fit)

2. **PPT and Online test will be on \_\_\_August, 2024**

**Interviews will be on \_\_\_\_August,2024**

3 Submit the details & resume to the below TIET Google link by 29th July, 2024 by 9.00 A.M

[**https://forms.gle/GFFtuxydc7yRQwLQA**](https://forms.gle/GFFtuxydc7yRQwLQA)

4. CTC ~  Stipend during internship for each profile.  And

Rs, 17.30 LPA (15L fixed)

Job location Noida, Pune, Mumbai, Hyderabad

Internship + FTE

(H.S.Bawa)

Head CILP

CC: HCSED/HEIED/HE&CED – for kind information please.

**THAPAR INSTITUTE OF ENGINEERING & TECHNOLOGY, PATIALA**

(Deemed to be University)

CENTRE FOR INDUSTRIAL LIAISON AND PLACEMENT

Dated: 24.07.2024

CAMPUS INTERVIEWS

1. Name of the Organization: **Axtria**

**(**[**www.axtria.com**](http://www.axtria.com)**)**

**Profile: Analyst**

Branches of Engineering: MCA

ME-CS

M.Sc -Mathematics & Computing / Maths

Eligibility Criteria 10TH 80%

10+2/ DIP 70%

Graduation 60%

Present CGPA 6.00

Process of Interviews: Shortlisting based upon details

Online test

Two rounds of Interviews

2. **PPT and Online test will be on \_\_\_August, 2024 .**

**Interviews will be on \_\_\_\_August,2024**

3 Submit the details & resume to the below TIET Google link by 29th July, 2024 by 9.00 A.M

[**https://forms.gle/8s3cDhkxxK4Syojk8**](https://forms.gle/8s3cDhkxxK4Syojk8)

4. CTC ~ Stipend during internship – Rs 25,000/- PM

Rs.13.00 LPA (10 Lakh + 1 Lakh joining bonus + 2 Lakh Paid

on first anniversary.)

Job location:  Noida, Bangalore, Hyderabad and Pune

Internship + FTE / Only FTE

(H.S.Bawa)

Head CILP

CC: HCSED/HSOM– for kind information please.

**THAPAR INSTITUTE OF ENGINEERING & TECHNOLOGY, PATIALA**

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CENTRE FOR INDUSTRIAL LIAISON AND PLACEMENT

Dated: 24.07.2024

CAMPUS INTERVIEWS

1. Name of the Organization: **Infinera**

**(www.**[**infinera.com**](https://nam11.safelinks.protection.outlook.com/?url=http%3A%2F%2Fwww.infinera.com%2F&data=05%7C01%7Cbchandak%40infinera.com%7C3b31fca3399f40ec79e008da79e668cc%7C285643de5f5b4b03a1530ae2dc8aaf77%7C1%7C0%7C637956327773050228%7CUnknown%7CTWFpbGZsb3d8eyJWIjoiMC4wLjAwMDAiLCJQIjoiV2luMzIiLCJBTiI6Ik1haWwiLCJXVCI6Mn0%3D%7C3000%7C%7C%7C&sdata=lH7MaZnUxdDnAWYEg8AYHp1PosLSts9HXY%2B9LExyx2k%3D&reserved=0)**)**

Branches of Engineering: BE- CS/EE/EIC/EC/ENC/EEC

Eligibility Criteria Present CGPA 8.00

No backlog courses at present.

Process of Interviews: Shortlisting based upon details

Offline written test

Two rounds of Interviews

2. **PPT and Online test will be on \_\_\_August, 2024**

**Interviews will be on \_\_\_\_August, 2024**

3 Submit the details & resume to the below TIET Google link by 29th July, 2024 by 9.00 A.M

[**https://forms.gle/ttEGJacrUqCSL14QA**](https://forms.gle/ttEGJacrUqCSL14QA)

4. CTC ~ Rs. 14.00 LPA fixed + 5% bonus

Rs. 40,000/- PM Stipend during internship

Job location: Bangalore

Internship + FTE

( H.S. Bawa )

Head CILP

CC: HCSED/HEIED/HE&CED – for kind information please.